

2026 IEEE INTERNATIONAL SYMPOSIUM ON
ELECTROMAGNETIC COMPATIBILITY
& SIGNAL/POWER INTEGRITY

AWARD WINNERS



EMC Society President’s Memorial Award
(Awarded in Memory of Takeo Yoshino)
Jinyan Ma
Zhejiang University
For exceptional contributions and dedication to electromagnetic compatibility for wireless communication systems through innovative algorithms and designs.

Richard R. Stoddart Award for Outstanding Performance
Ji Chen
For foundational contributions to EMC that transformed MRI safety assessment and patient access for implantable medical devices.

Laurence G. Cumming Award for Outstanding Service
Vignesh Rajamani
For outstanding leadership and sustained service to the EMC Society.

Excellence in Continuing EMC Engineering Education Award
Todd Hubing
For over 30 years of pioneering contributions to continuing EMC education in academic, industrial and EMC Society settings.

Technical Achievement Award
Xing-Chang Wei
For outstanding contributions to electromagnetic interference modeling and analysis based on advanced near-field scanning technology.

Technical Achievement Award
Olena Zhu
For contributions to end-to-end system design tools and methodologies using Artificial Intelligence, especially with regard to transformative signal integrity analysis of nonlinear circuits.

2026 John Howard Memorial EMC Education Grant
Sergiu Andreica
Technical University of Cluj-Napoca, Romania

2026 John Howard Memorial EMC Education Grant
Eve Klopf
High Point University, NC, USA

IEEE James C. Klouda Memorial Scholarship Award
Cannon Kilcrease
For outstanding performance as an undergraduate student pursuing a career in EMC.

Richard B. Schulz Best Transactions on EMC Paper Award – Honorable Mention
Jens Aigner, Maximilian Lemke, Tobias Dörlemann, Stephan Frei
“Broadband Active Common Mode EMI Suppression of a GaN Motor Inverter With Adaptive FIR Filters Using Delay-Compensated Gate Control Signals”
IEEE Transactions on Electromagnetic Compatibility | Year: 2025 | Volume: 67, Issue: 4

Richard B. Schulz Best Transactions on EMC Paper Award
Chih-Yu Fang, Bin-Chyi Tseng, Tzong-Lin Wu
“A Dual-Mode Decoupling Network for Differential- and Common-Mode Noise Suppression in High-Speed Connector Systems”
IEEE Transactions on Electromagnetic Compatibility | Year: 2025 | Volume: 67, Issue: 6

Motohisa Kanda Award for Most Cited (2021-2025) Transactions on EMC Paper Award
Huan Huan Zhang, Zhao Sheng Xue, Xin Yi Liu, Ping Li, Lijun Jiang, Guang Ming Shi
“Optimization of High-Speed Channel for Signal Integrity With Deep Genetic Algorithm”
IEEE Transactions on Electromagnetic Compatibility | Year: 2022 | Volume: 64, Issue: 4
Cited by: 73 Papers

Symposium Best Paper Award (EMC) – Honorable Mention
Katherine Dang, Pablo Narvaez, Samad Firdosy, Kevin Pham, Ian McKinley
“Design, Fabrication, and DC Magnetic Emission Testing of Additively Manufactured (3D-Printed) Magnetic Shields”

Symposium Best Paper Award (EMC)
Wenchang Huang, Shengxuan Xia, Xuechen Huang, Faizal Sainal Abdeen, Guangqiang Jiang, Chulsoon Hwang
“PMIC-Induced RF Desensitization Analysis in a Remote Device”

Symposium Best Paper Award (SIPI) – Honorable Mention
Sean S. Hwang, Kevin Cai, Felen Fu, Kai Li, Yan Li, Bidyut Sen
“Serpentine Traces Can be Faster Than Straight: Measurements, Physical Explanations, and Implications for High Speed PCB Design”

Symposium Best Paper Award (SIPI)
Weikai Luo, Da Li, Jinyan Ma, ErPing Li
“Inverse Design Method for Frequency Selective Surface Based on Physics-Informed Generative Models”

Best Student Paper Award (EMC) – Honorable Mention
Yuhao Xu, Jiarui Qiu, Yining Jiang, Pengqi Fu, Yuxiang Tian, Hanzhi Ma
“Potential-to-Field Neural Network for Efficient Electric Field Prediction”

Best Student Paper Award (EMC) –
Wenchang Huang, Shengxuan Xia, Xuechen Huang, Faizal Sainal Abdeen, Guangqiang Jiang, Chulsoon Hwang
“PMIC-Induced RF Desensitization Analysis in a Remote Device”

Best Student Paper Award (SIPI) – Honorable Mention
Junghyun Lee, Hyunjun An, Seungjae Lee, Keunwoo Kim, Youngsu Yoon, Byeongmok Kim, Haeseok Suh, Junho Park, Jaegeun Bae, Chaemin Yang, Gwantaek Lee, Joungho Kim
“Physics-Aware Tensor Learning for Data-Efficient Multi-Port Power Distribution Network Analysis”

Best Student Paper Award (SIPI) –
Sathvika Bandi, Manish Kizhakkeveetil Mathew, Shruti Sawant, Kevin Cai, Shameem Ahmed, Chulsoon Hwang
“Enhanced Intrinsic Via Model of High-Speed Vias”

Student EMC Hardware Design Competition – Winner
WWE (World-Wide EMC)
Missouri University of Science and Technology, Rolla, Missouri, USA;
Yejun Kim, Hariharan Prabakar, Sathvika Bandi, Cody Goins, Ahyeon Lee

Student EMC Hardware Design Competition – 1st Runner Up
Team Water-Loo
University of Waterloo, Waterloo, Ontario, Canada;
Jake Peters, Alanna Rudolph, Amirbahador Mansoori, Dhyey Bhatt

Student EMC Hardware Design Competition – 2nd Runner Up
Rose-Hulman Team 1
Rose-Hulman Institute of Technology, Terre Haute, Indiana, USA;
Yejia Hao, Jiuzhou Lin and Yicheng Zhu

Chapter-of-the-Year Award
IEEE Germany Section EMC Society Chapter
Chapter Founder Award
Gazi Alam
The Iowa Joint Sections EMC-S Chapter
For founding the Iowa Joint Sections EMC Society Chapter in May 2025 and serving as the first Chapter Chair.

Chapter Founder Award
Joshua Deaton
The Dallas EMC-S Chapter
For founding the Dallas, Texas EMC Society Chapter in October 2025 and serving as the first Chapter Chair.

Chapter Founder Award
Maresh Kala
The Delhi EMC-S Chapter, India
For founding the Delhi, India EMC Society Chapter in July 2025 and serving as the first Chapter Chair.

Chapter Founder Award
Nicolas Mora Parra
The Colombia (Suroccidente) Joint Chapter AP/EMC/MTT
For founding the Colombia (Suroccidente) Joint AP/EMC/MTT Chapter in July 2025 and serving as the first Chapter Chair.

Past Symposium Chair Award
Bruce Archambeault
For his leadership and dedication as General Chair of the 2025 IEEE International Symposium on Electromagnetic Compatibility and Signal/Power Integrity

CERTIFICATE OF
ACKNOWLEDGEMENT

Philippe Besnier
For outstanding service as Chair of the EMC Europe 2025 Symposium.

Hsi-Tseng Chou
For outstanding service as Chair of the 2025 Asia-Pacific International Symposium and Exhibition on Electromagnetic Compatibility (APEMC).

Han-Chang Hsieh
For outstanding service as Co-Chair of the 2025 Asia-Pacific International Symposium and Exhibition on Electromagnetic Compatibility (APEMC).

Jun Fan
For outstanding service as Co-Chair of the 2025 International Workshop on Advanced Interconnects (WAI).

Er-Ping Li
For outstanding service as Co-Chair of the 2025 International Workshop on Advanced Interconnects (WAI).

Antonio Maffucci
For outstanding service as Chair of the 2025 IEEE Workshop on Signal and Power Integrity (SPI).

Devendra Chandra Pande
For outstanding service as Chair of the 2025 International Conference on Electromagnetic Interference and Compatibility (INCEMIC).

CERTIFICATE OF APPRECIATION

Robert G. Olsen
For outstanding contributions as Associate Editor of the EMC Magazine from 2020 to 2025.

Carlos Sartori
For outstanding contributions as Associate Editor of the EMC Magazine from 2014 to 2025.

Benoit Derat, Roni Khazaka, Shibban Koul, Keith Frazier
For outstanding contributions to the administration and overall success of the EMC Society as Distinguished Lecturers (2024-2025).

Bruce Archambeault, Daryl Beetner, Zhong Chen, Krzysztof Sieczkarek, Mark Steffka, Nicolas Mora Parra
For outstanding contributions to the administration and overall success of the EMC Society as Members of the Board of Governors (2023-2025).

Kimball Williams
For outstanding service as Chair of the IEEE EMC Society Technical Committee on Electromagnetic Environment (TC3) in 2025.

William Radasky
For outstanding service as Chair of the IEEE EMC Society Technical Committee on High Power Electromagnetics (TC5) from 2003 to 2025.

Shuo Wang
For outstanding service as Chair of the IEEE EMC Society Technical Committee on Electrical System and Power Electronics EMC (TC7) from 2024 to 2025.

Flavia Grassi
For outstanding service as Chair of the IEEE EMC Society Technical Committee on Electrical System and Power Electronics EMC (TC7) from 2020 to 2025.

Randy Jost
For outstanding service as Chair of the IEEE EMC Society Technical Committee on Aeronautics and Space EMC (TC8) from 2024 to 2025.

Mike McInerney
For outstanding service as Chair of the IEEE EMC Society Special Committee on Smart Grid (SC1) from 2020 to 2025.

Alistair Duffy
For outstanding service as Chair of the IEEE EMC Society Special Committee on Machine Learning and Artificial Intelligence in EMC and SIPI (SC3) from 2023 to 2025.

Shuo Wang
For outstanding service as Chair of the IEEE EMC Society Special Committee on Power Electronics EMC (SC5) from 2017 to 2024.

Sven Battermann
For outstanding service during his term as Vice Chair of the IEEE Germany Section EMC Society Chapter from 2024 to 2025.

Sebastian Koj
For outstanding service during his term as Chair of the IEEE Germany Section EMC Society Chapter from 2024 to 2025

Dennis Lewis
For outstanding service as the Symposium Vice Chair for the 2026 IEEE International Symposium on EMC and SIPI.

Janet O’Neil
For outstanding service as the Symposium Advisor for the 2026 IEEE International Symposium on EMC and SIPI.

Bob Davis
For outstanding service as the Treasurer for the 2026 IEEE International Symposium on EMC and SIPI.

Patrick DeRoy
For outstanding service as the Secretary for the 2026 IEEE International Symposium on EMC and SIPI.

Benoit Derat
For outstanding service as the Technical Program Chair for the 2026 IEEE International Symposium on EMC and SIPI.

Lee Hill
For outstanding service as the Technical Program Vice Chair for the 2026 IEEE International Symposium on EMC and SIPI.

Flavia Grassi
For outstanding service as the Technical Papers Chair for the 2026 IEEE International Symposium on EMC and SIPI.

Niek Moonen
For outstanding service as the Student Paper Co-Chair for the 2026 IEEE International Symposium on EMC and SIPI.

Chuck Bunting
For outstanding service as the Student EMC Hardware Design Competition Chair for the 2026 IEEE International Symposium on EMC and SIPI.

Francesca Maradei
For outstanding service as the Special Sessions Co-Chair for the 2026 IEEE International Symposium on EMC and SIPI.

CERTIFICATE OF RECOGNITION

Rhonda Rodriguez
For outstanding service as the Exhibition and Sponsorship & Local Arrangements Co-Chair for the 2026 IEEE International Symposium on EMC and SIPI

Dale Stone
For outstanding service as the Exhibition and Sponsorship & Local Arrangements Co-Chair for the 2026 IEEE International Symposium on EMC and SIPI

Robin Zimmerman
For outstanding service as the Volunteers Chair for the 2026 IEEE International Symposium on EMC and SIPI

Pablo Ruiz Morales
For outstanding service as the Student Paper Co-Chair for the 2026 IEEE International Symposium on EMC and SIPI

Colin Petherbridge
For outstanding service as the Youth Technical Program Chair for the 2026 IEEE International Symposium on EMC and SIPI

CONGRATULATIONS
to the following EMC Society Members who were elected to the IEEE Fellow Grade in 2026.
These members are shown below with their evaluating Society

Paul Svasta , <i>Electronics Packaging Society</i>	Natalia Litchinitser , <i>Photonics Society</i>
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IN MEMORIAM

Billy Martin (1956 - 2025) Edward Hare (1950 - 2025)	Jasper Goedbloed (1937 - 2025) Russell Carstensen (1942 - 2020) Tasuku Takagi (1932 - 2024)
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TRANSACTIONS ON EMC:
2025 DISTINGUISHED REVIEWERS

Yuichi Hayashi
Nara Institute of Science and Technology, Ikoma, Japan

William Radasky
Metatech Corporation, California, United States

Richard Xian-Ke Gao
Institute of High-Performance Computing Electronics and Photonics, Singapore

Zacharias Datsios
Aristotle University of Thessaloniki, Thessaloniki, Greece

Mathias Magdowski
Otto von Guericke University, Magdeburg, Germany

Pavithrkrishnan Radhakrishnan
Oklahoma State University, Oklahoma, United States

Peng Hu
Southeast University, Nanjing, Jiangsu, China

Guillaume Andrieu
University of Limoges, XLIM Laboratory, Limoges, France

Huamin Jie
Nanyang Technological University, Singapore

Yinling Diao
South China Agricultural University, Guangzhou, China

Da Yi
Chongqing University, Chongqing, China

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